

# iesy ESP32 OSM-oF

OSM™ - The standard for solder-on computer modules

## Technical Data

- ▶ Microcontroller: ESP32 Xtensa DualCore x32 LX6
- ▶ Clock rate: 240 MHz
- ▶ RAM: 512 KB
- ▶ Flash memory: 32 Mbit SPI-Flash
- ▶ Dimension: 15 mm x 30 mm
- ▶ Footprint: OSM Size-0 Land Grid Array (LGA), Solder-on modules with 188 contact points
- ▶ Power supply: 3,3 V, +/- 5 % via LGA contacts
- ▶ Power consumption: <1 W (typ.)
- ▶ Temperature range:
  - > Operating: -40 °C to +80 °C
  - > Storage: -40 °C to +85 °C
- ▶ Software: Espressif IDE (FreeRTOS based) via PlatformIO
- ▶ **Features & Interfaces:**
  - > Wi-Fi 802.11 b/g/n + Bluetooth/BLE
  - > 1 x LAN 10/100 (RMII), MAC compatible with IEEE 802.3
  - > 1x OSM Antenna-Contact / U.FL-Connector (optionally)
  - > 1x SDIO-Card
  - > 1x I2C
  - > 2x ADC
  - > 4x GPIO
  - > 2x UART
  - > 1x SPI

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## Features

The smallest solder-on module from the OSM™ series is smaller than a standard stamp. The area of application is therefore clear - small for small. The focus here is primarily on various applications from the consumer electronics environment. But the “dwarf” also has its right to exist for tasks in the industrial environment. Despite its small size, the OSM™ Size-0 (Zero) does not have to hide. In terms of performance, it covers numerous core functions very well. In addition, the Size-0, like all Open Standard Modules™, offers the possibility to respond flexibly to requirements.



**iesy** is a specialist for embedded computing solutions.. Driven by our passion for technology we have been developing electronic systems since 1966. With a team of experts in soft- and hardware development, manufacturing and device testing, we are an ideal outsourcing partner for the development, prototyping, series production and maintenance of customer-specific electronic products. **This is simple. This is iesy.**